

IN THE CLAIMS:

This listing of the claims replaces all prior versions and listings of the claims in this application.

The text of all pending claims (including any withdrawn claims) is set forth below. Canceled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (Original), (Currently amended), (Canceled), (Withdrawn), (Previously presented), (New), and (Not entered).

Please AMEND claims 14 and 18, CANCEL claim 20 without prejudice or disclaimer of the subject matter thereof, and ADD new claim 21 in accordance with the following:

1. (Withdrawn) A deposition mask frame assembly comprising:
a mask comprising a thin plate in which a predetermined pattern of apertures is formed;
a frame supporting one surface of the mask so that the mask is tensed; and
a cover mask supporting an opposite surface of the mask, wherein the cover mask corresponds to the frame.
2. (Withdrawn) The deposition mask frame assembly of claim 1, wherein the mask is formed of nickel or an alloy of nickel and cobalt.
3. (Withdrawn) The deposition mask frame assembly of claim 2, wherein the mask is formed by electro-forming.
4. (Withdrawn) The deposition mask frame assembly of claim 1, wherein the mask, the frame, and the cover mask are joined together by welding.
- 5 (Withdrawn) The deposition mask frame assembly of claim 4, wherein the welding is a dot welding.
6. (Withdrawn) The deposition mask frame assembly of claim 5, wherein a welding pitch between welding dots is 3mm or less.

7. (Withdrawn) The deposition mask frame assembly of claim 1, wherein the cover mask is configured so as to support the four edges of the mask.

8. (Withdrawn) A method of manufacturing a deposition mask frame assembly, the method comprising:

electrodepositing a metal on an electrodepositing plate using an electro-forming method, wherein the metal is electrodeposited to a predetermined thickness, and the electrodepositing plate has a film attached corresponding to shielding portions that form an outer portion of a mask and define apertures in the mask;

separating the mask from the electrodepositing plate; and

installing a frame on one surface of the mask and installing a cover mask on the other surface of the mask while the mask is being tensed, and welding the cover mask, the mask, and the frame.

9. (Withdrawn) The method of claim 8, wherein the predetermined thickness is 30-50 μ m.

10. (Withdrawn) The method of claim 8, wherein the mask comprises nickel or an alloy of nickel and cobalt.

11. (Withdrawn) The method of claim 8, wherein the inner circumference of the cover mask is larger than an outer circumference of a substrate on which a layer is deposited.

12. (Withdrawn) The method of claim 8, wherein different tensions are applied to different sides of the mask to reduce a deviation of a total pitch of apertures and a line deviation.

13. (Withdrawn) The method of claim 8, wherein a portion of the cover mask and an edge of the mask are cut off to match a size and shape of the mask and the cover mask with the frame.

14. (Currently amended) A method of manufacturing an organic EL device, the method comprising:

forming a first electrode layer in a predetermined pattern on an insulating substrate;
forming an organic film comprising at least a patterned emission layer on the first electrode layer;
forming a second electrode layer in a predetermined pattern on the organic film; and
sealing the second electrode layer,
wherein at least one of the organic film and the second electrode layer is deposited using a deposition mask frame assembly, the deposition mask frame assembly comprising:

a mask comprising a thin plate in which a predetermined pattern of apertures is formed;

a frame supporting one surface of the mask so that the mask is tensed; ~~wherein the frame has a flat surface where the frame supports the one surface of the mask; and~~

a cover mask supporting an opposite surface of the mask; ~~wherein the cover mask corresponds to the frame and has a flat surface where the cover mask supports the opposite surface of the mask~~

wherein all surfaces of the frame facing the one surface of the mask lie in a same first plane; and

wherein all surfaces of the cover mask facing the opposite surface of the mask lie in a same second plane.

15. (Original) The method of claim 14, wherein the mask is formed of nickel or an alloy of nickel and cobalt.

16. (Original) The method of claim 14, wherein the mask is formed by electro-forming.

17. (Original) The method of claim 14, wherein the mask, the frame, and the cover mask are joined together by welding.

18. (Currently amended) The method of claim 17, wherein the welding is a-dot welding.

19. (Original) The method of claim 18, wherein a welding pitch between welding dots is 3mm or less.

20. (Canceled)

21. (New) The method of claim 14, wherein the mask is tensed with a tension that varies depending on a position in the mask.